

Super Low Noise HEMT

FEATURES

- Low Noise Figure:0.45dB(Typ.)@f=12GHz(FHX13)
- High Associated Gain : 13.0dB(Typ.)@f=12GHz
- Lg ≤0.15µm, Wg=200µm
- · Gold Gate Metallization for High Reliability
- Cost Effective Ceramic Microstrip (STM) Package
- Tape and Reel Packaging Available

DESCRIPTION

The FHX13LG,FHX14LG is a Super High Electron Mobility Transistor(SuperHEMT [™]) Intended for general purpose, ultra-low noise and high gain amplifiers In the 2 to18GHz frequency range. The devices are packaged in cost effective, low parasitic, hermetically sealed metal-ceramic package for high volume telecommunication,TVRO,VSAT or other low noise applications.

Sumitomo's stringent Quality Assurance Program assures the highest reliability and consistent performance.

ABSOLUTE MAXIMUM RATING (Case Temperature Tc=25deg.C)

Item	Symbol	Rating	Unit
Drain-Source Voltage	V _{DS}	3.5	V
Gate-Source Voltage	V _{GS}	-3	V
Total Power Dissipation	P _{T*}	180.0	mW
Storage Temperature	T _{stg}	-65 to +175	deg.C
Channel Temperature	T _{ch}	175	deg.C

*Note:Mounted on Al₂o₃ board(30 x 30 x 0.65mm)

Sumitomo recommends the follow ing conditions for the reliable operation of GaAs FETs:

- 1. The drain-source operating voltage (V $_{\mbox{\scriptsize DS}}$) should not exceed 2 volts.
- 2. The forw ard and reverse gate currents should not exceed 0.2 and -0.05 mA respectively with
- gate resistance of 4000ohm.
- 3. The operating channel temperature(Tch) should not exceed 80deg.C.

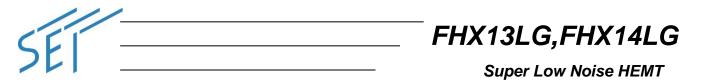
ELECTRICAL CHARACTERISTICS (Case Temperature Tc=25deg.C)

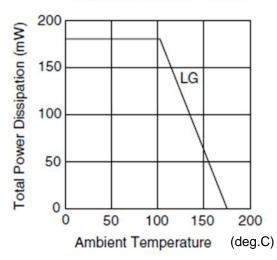
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ltem	Symbol	rest conditions	Min.	Тур.	Max.	Unit	
Saturated Drain Current		I _{DSS}	V _{DS} =2V, V _{GS} =0V	10	30	60	mA
Transconductance		g _m	V _{DS} =2V, I _{DS} =10mA	35	50	-	mS
Pinch-off Voltage		Vp	V _{DS} =2V, I _{DS} =1mA	-0.1	-0.7	-1.5	V
Gate Source Breakdown Voltage		V _{GSO}	I _{GS} =-10uA	-3.0	-	-	V
Noise Figure	FHX13LG	NF	V _{DS} =10V,	-	0.45	0.50	dB
Associated Gain	FINISLG	Gas		11.0	13.0	-	dB
Noise Figure	FHX14LG	NF	I _{DS} =10mA,	-	0.55	0.60	dB
Associated Gain		Gas	f=12GHz	11.0	13.0	-	dB
Thermal Resistance R _{th}		R _{th}	Channel to Case	-	300	400	deg.C/V

Note : RF parameters for LG devices are measured on a sample basis as follows:

Lot Qty.	Sample Qty.	Accept/Reject			
1200 or less	125	(0,1)			
1201 to 3200	200	(0,1)			
3201 to 10000	315	(1,2)			
10001 or over	500	(1,2)			
CASE STYLE		LG			
RoHS Compliance		Yes			

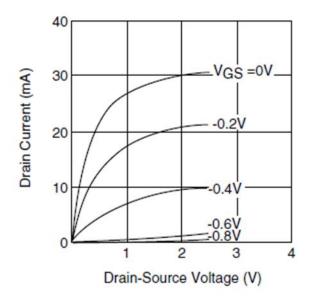






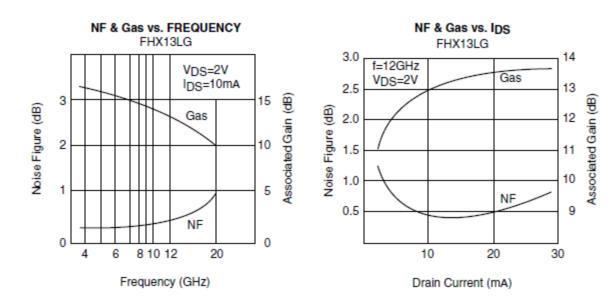
POWER DERATING CURVE

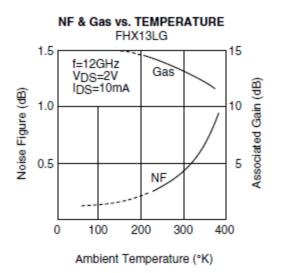
DRAIN CURRENT vs. DRAIN-SOURCE VOLTAGE



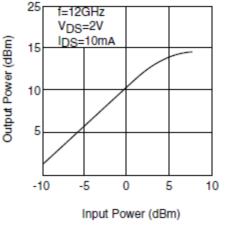


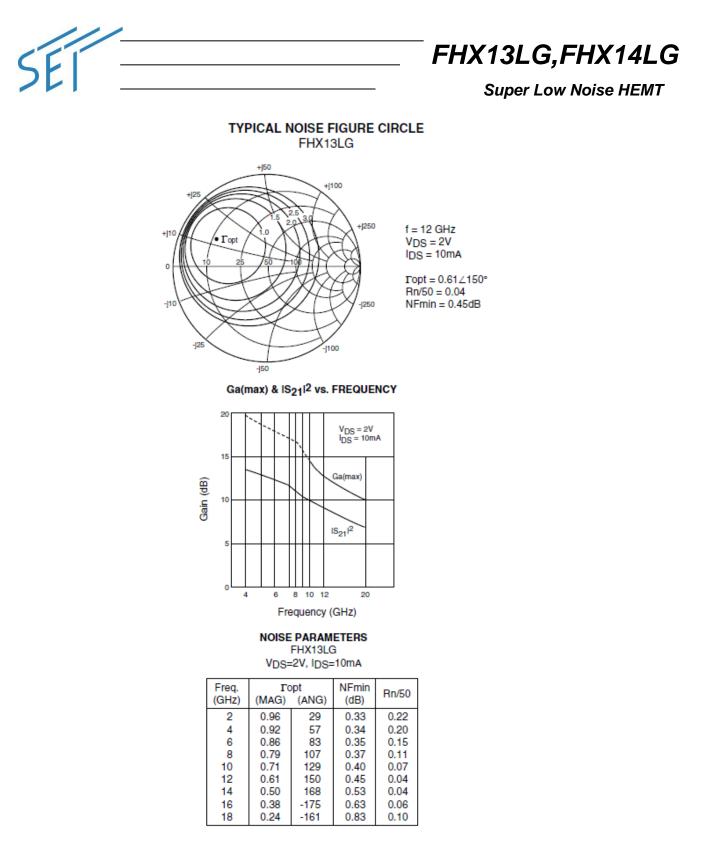
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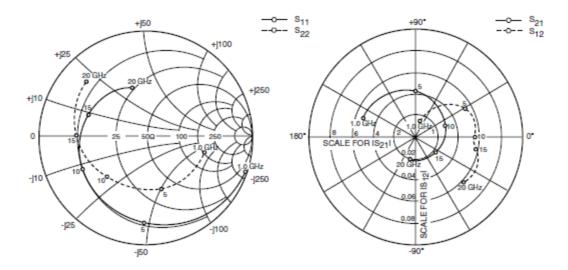
OUTPUT POWER vs. INPUT POWER FHX13LG







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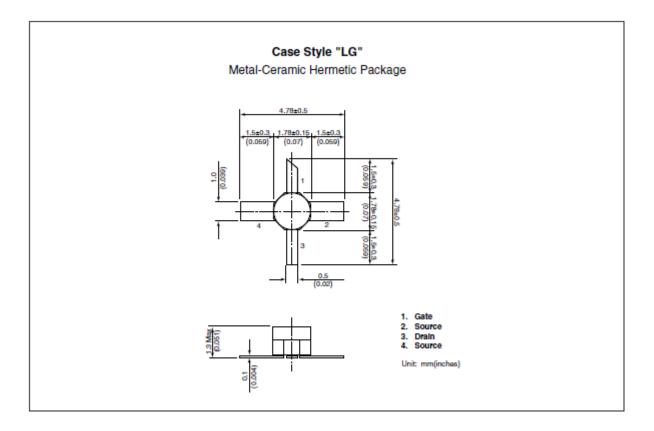


S-PARAMETERS FHX13/14LG

	$V_{DS} = 2V$, $I_{DS} = 10mA$							
FREQUENCY	S	S11 S21		S	S12		S22	
(MHZ)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
1000	0.000		5 007		0.045			10.0
1000	0.988	-20.0	5.327	160.1	0.015	75.7	0.574	-16.3
2000	0.956	-39.5	5.133	141.0	0.028	63.3	0.560	-32.1
3000	0.908	-58.1	4.851	123.0	0.039	50.1	0.539	-47.3
4000	0.862	-75.5	4.534	105.9	0.048	39.0	0.522	-62.0
5000	0.811	-91.6	4.213	89.7	0.053	29.3	0.502	-75.6
6000	0.763	-107.1	3.886	74.4	0.056	21.0	0.488	-89.6
7000	0.727	-121.1	3.582	60.0	0.057	13.2	0.487	-103.0
8000	0.701	-133.3	3.300	46.4	0.056	7.9	0.498	-114.9
9000	0.682	-144.1	3.078	33.8	0.055	3.5	0.515	-125.0
10000	0.659	-154.2	2.899	21.4	0.055	-0.0	0.531	-134.4
11000	0.636	-164.4	2.748	9.3	0.054	-2.6	0.544	-144.0
12000	0.618	-175.4	2.593	-3.3	0.054	-5.2	0.561	-155.1
13000	0.608	175.5	2.466	-14.8	0.054	-5.7	0.590	-164.0
14000	0.596	166.6	2.366	-26.6	0.055	-7.8	0.619	-172.4
15000	0.585	158.3	2.279	-38.3	0.056	-9.7	0.654	-179.7
16000	0.564	148.8	2.244	-50.7	0.058	-12.8	0.677	172.6
17000	0.543	138.2	2.217	-63.6	0.061	-17.6	0.701	163.4
18000	0.525	127.3	2.185	-77.1	0.063	-24.7	0.727	154.1
19000	0.506	116.2	2.143	-91.4	0.063	-33.1	0.748	143.6
20000	0.470	106.5	2.089	-105.4	0.061	-43.7	0.763	137.2



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CAUTION

This product contains **gallium arsenide (GaAs)** which can be hazardous to the human body and the environment. For safety, observe the following procedures:

• Do not put these products into the mouth.

• Do not alter the form of this product into a gas, powder, or liquid through burning, crushing, or chemical processing as these by-products are dangerous to the human body if inhaled, ingested, or swallowed.

• Observe government laws and company regulations when discarding this product. This product must be discarded in accordance with methods specified by applicable hazardous waste procedures.